				ATTY. DOCKET NO.:		APPLICATION NO.:			
LIST OF REFERENCES CITED BY APPLICANT Form PTO-1449 (Use several sheets if necessary)					4717-11500		10/716,451		
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					Fabrice LETERTRE FILING DATE: GROUP:				
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*EXAMINER INITIAL	CITE NO.	DOCUMENT NUMBER	DATE	NAME		CLASS	SUBCLASS		DATE IF PRIATE
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*EXAMINI					conformance with MPEP 60	09. Draw line	through cita	tion if	not in
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